

Copper Foil with Aluminum Carrier

DATASHEET



□ Benefits

Improve Your Yields

- Protect the copper surface
- Eliminate Epoxy Spots
- Reduce Pits and Dents due to airborne particulate
- Buffers the Copper Foil from damaged Separator Plates

Improve Your Productivity

- Speeds up the Layup Process
- Improves handling of thin Copper Foils
- Suitable for Automated Handling Systems
- Can replace expensive Copper/Aluminum/Copper and Aluminum/Bonded/Copper products

□ Description

ACF2: Single-sided Copper-Aluminum Layer

ACF3: Double-sided Copper-Aluminum-Copper Layer

Advanced Copper Foil is a company dedicated to High Performance Copper Foils and their applications in the Printed Circuit and Battery Shielding Industries. ACF2 and ACF3 are two products that facilitate the PCB layup process and provide a carrier for ultra-thin foils.

Manufactured in a clean-room, the ACF family of products guarantee a pristine copper surface, free of debris and other foreign materials. These products also protect the copper surface from epoxy spots and finger prints during the Multilayer Layup process.

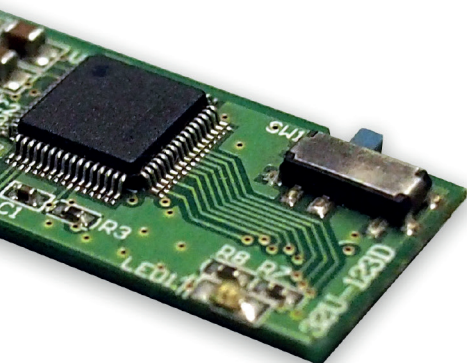
Advanced Copper Foil is committed to providing PCB Fabricators, Laminate Manufacturers and Battery Shielding Companies with a cost-effective alternative to the traditional products on the market today. Please contact us for free samples for evaluation.

ACF2™

This product is comprised of one piece of copper foil and one panel of aluminum. It is designed as a carrier sheet for the top or bottom copper layer in an MLB. The loose copper sheet is attached to the aluminum carrier with an inert adhesive.

ACF3™

This product is comprised of two pieces of copper foil and one panel of aluminum. It can be used as the top and bottom copper layers in a multiple MLB stackup. Please refer to the diagram on the reverse side.



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Specification

Copper Foil

ACF is available with different copper foil types:

- Standard copper, HTE (IPC Grade-3) for conventional FR-4 circuit boards
- High bond strength copper, for BT and Polyimide
- And Very Low Profile copper, for advanced HSLC applications

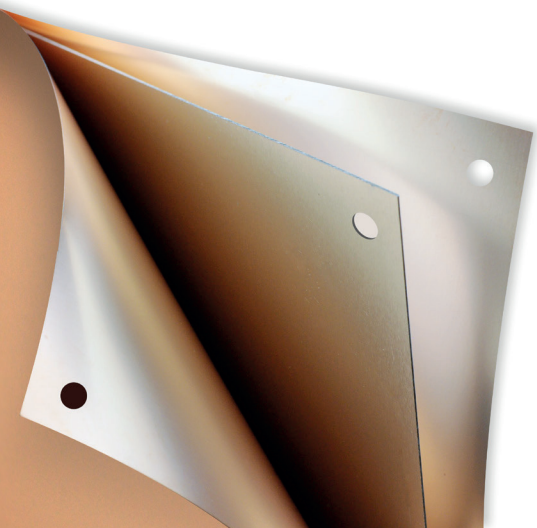
ACF is available in different copper foil thicknesses:

Thickness	
9 μm	0.25 oz
12 μm	0.375 oz
18 μm	0.5 oz
35 μm	1.0 oz
70 μm	2.0 oz

Aluminum

ACF Aluminum is available as follows:

Grade	Thickness	
3000-series	.007"	0.18 mm
	.010"	0.25 mm
	.015"	0.38 mm



Adhesive

ACF is built with an "inert adhesive" that becomes weaker with heat. After the lamination cycle, the aluminum separators are easily broken-down.

Panel Sizes

Panels are available in sizes 12" x 18" through 25" x 43".

Tooling Configuration

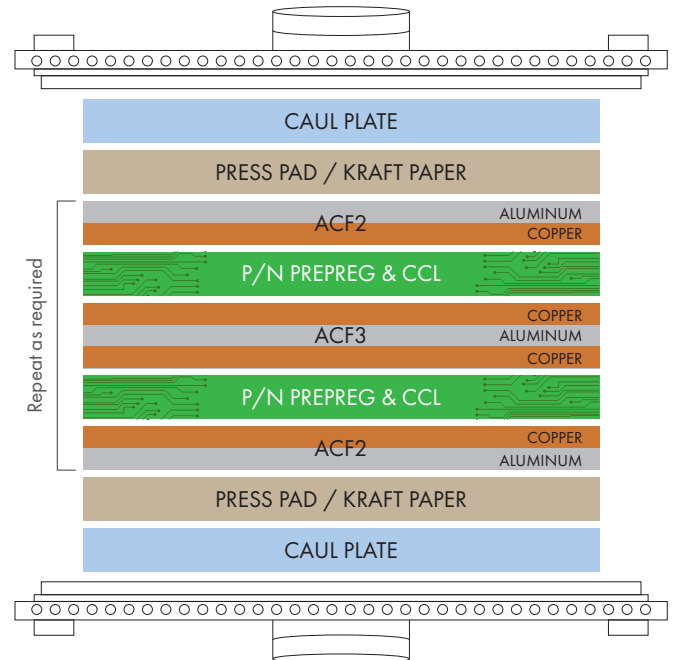
All panel sizes are available with standard multi-line tooling (0.188" offset in one short dimension). Other configurations are available on special order basis.

Processing Guidelines

For best results, refer to the CCL and PPG manufacturer's recommendations for lamination cycles.

Storage

Store flat and at ambient temperatures.



For more info, visit our website at advancedcopperfoil.com

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